

BOARD-TO-BOARD HEADERS & RECEPTACLES



✓ Active

TE CONNECTIVITY (TE)

FB-5R,ASY,300,SIG,HDR,SL,4.25

Z-PACK | Future Bus+

5223000-1

TE Internal Number: 5223000-1

EU RoHS Compliant EU ELV Compliant

Connector Style Plug

Number of Positions 30

Centerline (Pitch) 2 mm [.079 in]

Packaging Method Tube

Contact Mating Area Plating Material Gold



PRODUCT DRAWING

English



★ 3D PDF

DOCUMENTATION

Product Drawings

ASSEMBLY, PIN, SIGNAL, VERTICAL, Z-PACK 2mm FB, 5 ROW, SOLDER LEAD

PDF (TIFF AVAILABLE)

English

CAD Files

Customer View Model

2D_DXF.ZIP

English

Customer View Model

3D_IGS.ZIP

English

3D_STP.ZIP **English** 3D PDF **PDF English Product Specifications Application Specification Z-PACK 2 Mm FB (Futurebus+) Receptacle And Pin Header Connectors** PDF **English Product Specification** Connector, Z-PACK*, 2 Mm FB, Signal And Power PDF **English Qualification Test Report** Connector, Z-PACK, 2mm FB, Signal & Power TIF **English** Connector, Z-PACK, 2mm FB, Signal & Power PDF **English** Connector, Z-PACK, 2mm FB, Signal & Power PDF **Japanese** Product Environmental Compliance TE Material Declaration MD_5223000-1_072120141150_dmtec PDF **English FEATURES** Please review product documents or contact us for the latest agency approval information. Please Note: Use the Product Drawing for all design activity. **Product Type Features** Module Type Signal **Connector Style** Plug Connector & Contact Terminates To Printed Circuit Board Post Type Solder Post Row-to-Row Spacing 2 mm [.079 in] **PCB Mounting Orientation** Vertical **Connector Type** Header **Boss** Without

Product Type Connector

Customer View Model

Configuration Features

Stackable No

Number of Positions 30

Number of Rows 5

Sequencing No

Number of Signal Positions 30

Electrical Characteristics

Dielectric Withstanding Voltage (VAC) 1000

Voltage (VAC) 30

Insulation Resistance (M Ω) 100 – 5000

Body Features

Post Plating Material Tin

Contact Features

Solder Tail Contact Plating Material Tin

Contact Mating Area Plating Material Gold

Contact Mating Area Plating Thickness .05 µm [1.9685 µin]

Contact Current Rating (Max) (A) 3

Solder Tail Contact Plating Thickness 3.81 µm [149.9997 µin]

Contact Layout Matrix

Contact Base Material Phosphor Bronze

Contact Type Pin

Termination Features

Termination Method to PC Board Through Hole

Termination Post Length 4.25 mm [.167 in]

Interface Type Futurebus+

Mechanical Attachment

Mating Alignment Type Polarization

PCB Mount Retention Without

Housing Features

Centerline (Pitch) 2 mm [.079 in]

Housing Material LCP (Liquid Crystal Polymer)

Housing Color Natural

Dimensions

Mating Post Length 6.5 mm [.256 in]

Height 17 mm [.6681 in]

Tail Length 4.25 mm [.22 in]

Width 18 mm [.709 in]

Usage Conditions

Operating Temperature Range (°C) -55 – 125

Operation/Application
Pick and Place Cover Without

Packaging Features
Packaging Method Tube
Packaging Quantity 48

Other
Comment Sequencing of the mating posts and lead lengths is available. Worksheets for this procedure may be found under Z-PACK 2mm FB General Information.

Statement of Compliance

Statement of Compliance

PDF